



Material Content Data Sheet



Sales Product Name		BTF6070-2EKV		Issued		14. September 2018		
MA#		MA001837652						
Package		PG-DSO-14-40		Weight*		149.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.675	1.79	1.79	17919	17919
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		117	
	non noble metal	zinc	7440-66-6	0.070	0.05		466	
	non noble metal	iron	7439-89-6	1.392	0.93		9323	
wire	non noble metal	copper	7440-50-8	56.512	37.86	38.85	378567	388473
	non noble metal	copper	7440-50-8	0.425	0.28	0.28	2846	2846
	encapsulation	organic material	carbon black	1333-86-4	0.169	0.11		1135
plastics	plastics	epoxy resin	-	7.791	5.22		52192	
	inorganic material	silicondioxide	60676-86-0	76.726	51.41	56.74	513979	567306
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8214	8214
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9496	9496
glue	plastics	epoxy resin	-	0.150	0.10		1006	
	noble metal	silver	7440-22-4	0.708	0.47	0.57	4740	5746
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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